# 502600104 12/12/2013

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2646417

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
HYUNGGON RYU	11/27/2013
YOUNGHO KIM	11/27/2013
JINWAN BAE	11/27/2013

#### RECEIVING PARTY DATA

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### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	29476231

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NAME OF SUBMITTER:	ROBERT J. GOODELL
Signature:	/Robert J. Goodell/
Date:	12/12/2013

Total Attachments: 2

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PATENT REEL: 031772 FRAME: 0290 10.00 29476

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ATTORNEY DOCKET NO.: SOLE/JOINT INVENTION (U.S. Rights Only)

### ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

### MOBILE PHONE

1.10 - 1-
for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on, (Application No); and
WHEREAS, LG ELECTRONICS INC., a corporation of Republic of Korea, whose post office address is 20 Yeouido-dong Yeongdeungpo-gu Seoul 150-721 Republic of Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;
NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;
AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this

invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

and Power of Attorney in this application, to ins	quest the attorneys I/WE have empowered sert here in parenthesis (Application Nonumber of said application when known.	in the Declaration , filed
IN TESTIMONY WHEREOF, I/WE ha	ave hereunto set our hand(s).	
Full Name of First Assignor Hyunggon RYU	Assignor's Signature	Date 2014, 11.211
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Names of additional inventors attached Yes	□No	3000

**REEL: 031772 FRAME: 0291** 

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RECORDED: 12/12/2013 REEL: 031772 FRAME: 0292